

Title (en)

Die bonder and/or wire bonder with a suction device for pulling flat and holding down a curved substrate

Title (de)

Die Bonder und/oder Wire Bonder mit einer Ansaugvorrichtung zum Flachziehen und Niederhalten eines gewölbten Substrats

Title (fr)

Connecteur de puce et/ou unité de connexion de fils comprenant un dispositif d'aspiration pour le redressement de substrat courbé

Publication

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Application

EP 00811195 A 20001214

Priority

- EP 00811195 A 20001214
- EP 99811159 A 19991214

Abstract (en)

A Die Bonder or Wire Bonder has a suction device for pulling flat and holding down a curved substrate (3) equipped with or to be equipped with a semiconductor chip onto a supporting surface (2) of a plate (1). The plate (1) contains at least one cavity (7) open towards the supporting surface (2) in which there is a vacuum gripper (8.1; 8.2; 8.3; 8.4) made out of flexible material, whereby the vacuum gripper (8.1; 8.2; 8.3; 8.4) is lowerable into the cavity (7) during transport of the substrate (3) and which is raisable above the level of the supporting surface (2) to apply suction to the substrate (3). <IMAGE>

IPC 1-7

H01L 21/00; **B25B 11/00**

IPC 8 full level

B25B 11/00 (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP)

B25B 11/005 (2013.01); **H01L 21/6838** (2013.01)

Citation (search report)

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